- 8-Bit Parallel-Out Storage Register Performs Serial-to-Parallel Conversion with Storage
- Asynchronous Parallel Clear
- Active High Decoder
- Enable/Disable Input Simplified Expansion
- Expandable for N-Bit Applications
- Four District Functional Modes
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

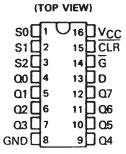
#### description

These 8-bit addressable latches are designed for general purpose storage applications in digital systems. Specific uses include working registers, serial-holding registers, and active-high decoders or demultiplexers. They are multifunctional devices capable of storing single-line data in eight addressable latches, and being a 1-of-8 decoder or demultiplexer with active-high outputs.

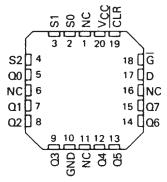
Four distinct modes of operation are selectable by controlling the clear (CLR) and enable (G) inputs as enumerated in the function table. In the addressable-latch mode, data at the data-in terminal is written into the addressed latch. The addressed latch will follow the data input with all unaddressed latches remaining in their previous states. In the memory mode, all latches remain in their previous states and are unaffected by the data or address inputs. To eliminate the possiblity of entering erroneous data in the latches, enable G should be held high (inactive) while the address lines are changing. In the 1-of-8 decoding or demultiplexing mode, the addressed output will follow the level of the D input with all other outputs low. In the clear mode, all outputs are low and unaffected by the address and data inputs.

The SN54259 and SN54LS259B are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74259 and SN74LS259B are characterized for operation from 0°C to 70°C.

SN54259, SN54LS259B . . . J OR W PACKAGE SN74259 . . . N PACKAGE SN74LS259B . . . D OR N PACKAGE

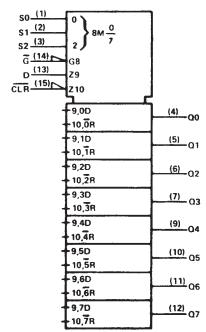


# SN54LS259B . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

# logic symbol†



<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



#### **FUNCTION TABLE**

CLR	s G	OUTPUT OF ADDRESSED LATCH	EACH OTHER OUTPUT	FUNCTION
н	L	D	Q <sub>iO</sub>	Addressable Latch
н	Н	Q <sub>iO</sub>	Q <sub>i0</sub>	Memory
L	L.	D	L	8-Line Demultiplexer
L	Н	L	L	Clear

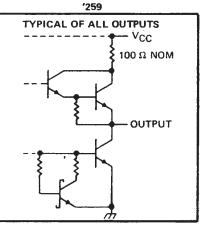
 $H \equiv high\ level,\ L \equiv low\ level$ 

#### **LATCH SELECTION TABLE**

SEL	ECT IN	IPUTS	LATCH
S2	S1	SO	ADDRESSED
L	L	L	0
L	L	H	1
L	Н	L	2
L	Н	H	3
н	L	L	4
Н	L	Н	5
Н	Н	L	6
Н	Н	н	7

schematic of inputs and outputs 259

**EQUIVALENT OF EACH INPUT** Vcc-Req INPUT  $\overline{G}\colon \ R_{eq} = 2.2 \ k\Omega \ NOM$  All other inputs:  $R_{eq} = 4 \ k\Omega \ NOM$ 



'LS259B 'LS259B 'LS259B EQUIVALENT OF GINPUT **EQUIVALENT OF ALL OTHER INPUTS** TYPICAL OF ALL OUTPUTS - VCC 120 Ω NOM Vcc-VCC  $R_{eq}$  = 17 k $\Omega$  NOM  $10 \text{ k}\Omega \text{ NOM}$ INPUT: INPUT: OUTPUT

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage (see Note 1)			7 V
Input voltage: SN54259, SN74259			5.5 V
Operating free-air temperature range:	SN54259, SN54LS259B	3	$-55^{\circ}$ C to $125^{\circ}$ C
	SN74259, SN74LS259B	}	0°C to 70°C
Storage temperature range	· · · · · · · · · · · · · · · · · · ·		$-65^{\circ}$ C to $150^{\circ}$ C

NOTE 1: Voltage values are with respect to network ground terminal.



D ≡ the level at the data input

 $Q_{i0} \equiv$  the level of  $Q_i$  (i = 0, 1, . . . 7, as appropriate) before the indicated steady-state input conditions were established.

# recommended operating conditions

		SN54	259	SN742	259	UNIT
		MIN NO	MAX	MIN NO	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.5	5 5.5	4.75	5 5.25	V
High-level output current, IOH			-800		800	μΑ
Low-level output current, IOL			16		16	mA
Width of clear or enable pulse, tw		15		15		ns
	Data	15↑		151		
Setup time, t <sub>gU</sub>	Address	5↑		5↑		ns
11.11.1	Data	0↑		01		
Hold time, th	Address	20↑		20†		ns
Operating free-air temperature, TA		-55	125	0	70	°C

<sup>†</sup>The arrow indicates that the rising edge of the enable pulse is used for reference.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED		TEST OF	NDITIONS†	S	N5425	9		N7425	9	UNIT
	PARAMETER		I EST CC	יפאטוווטאקי	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
ViH	High-level input voltag	e			2			2			V
VIL	Low-level input voltage	•					0.8			0.8	V
VIK	Input clamp voltage		V <sub>CC</sub> = MIN,	I <sub>I</sub> = 12 mA			-1.5			-1.5	V
Voн	High-level output volta	ge	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -800 μA	2.4	3.4		2.4	3.4		V
VOL	Low-level output volta	v-level output voltage		V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	٧
I <sub>I</sub>	Input current at maxin	num input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V			1			1	mA
	High-level input	Ğ	1/ - 11A V	V = 2.4 V	ĺ		80			80	
ΙΗ	current	Other inputs	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V			40			40	μА
	Low-level input	G	V - 444 V	V - 0 4 V	Ī		-3.2			-3.2	
HL	current	Other inputs	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V			-1.6			-1.6	mA
los	Short-circuit output cu	ırrent§	V <sub>CC</sub> = MAX		-18		-57	-18		<b>–</b> 57	mA
Icc	Supply current		V <sub>CC</sub> = MAX,	See Note 2		60	90	1	60	90	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, VCC = 5 V, TA = 25°C

FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
CLR	Any Q			16	25	ns
S		1		14	24	ns
Data	Any u	CL = 15 pF,		11	20	7 "
		$R_L = 400 \Omega$ ,		15	28	ns
Address	Any u	See Note 3		17	28	7 '''
_		1		12	20	ns
G	Any Q			11	20	7 '''
	(INPUT)	(INPUT) (OUTPUT)  CLR Any Q  Data Any Q  Address Any Q	(INPUT) (OUTPUT)  CLR Any Q  Data Any Q  CL = 15 pF,  RL = 400 Ω,  See Note 3	(INPUT)         (OUTPUT)         TEST CONDITIONS         MIN           CLR         Any Q         CL = 15 pF,           Address         Any Q         RL = 400 Ω,           See Note 3         See Note 3	(INPUT)         (OUTPUT)         TEST CONDITIONS         MIN         TYP           CLR         Any Q         16           Data         Any Q         14           Address         Any Q         R <sub>L</sub> = 400 Ω, See Note 3         15           See Note 3         17	(INPUT)         (OUTPUT)         TEST CONDITIONS         MIN         TYP         MAX           CLR         Any Q         16         25           Data         Any Q         14         24           CL = 15 pF,         11         20           RL = 400 $\Omega$ ,         15         28           See Note 3         17         28           Image: Control of the control of t

t<sub>PLH</sub> = propagation delay time, low-to-high-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>\</sup>ddagger$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_{A} = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time,

NOTE 2:  $I_{\mbox{\footnotesize{CC}}}$  is measured with the inputs grounded and the outputs open.

tpHL = propagation delay time, high-to-low-level output

### recommended operating conditions

			SI	154LS2	59B	SN	174LS25	59B	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
ЮН	High-level output current				- 0.4			- 0.4	mA
IOL	Low-level output current				4			8	mA
_	Pulse duration	G low	17			17			
t <sub>W</sub>	ruise duration	CLR low	10			10			, ns
		Data before G †	20			20			
t <sub>su</sub>	Set up time	Address before G†	17			17			пs
		Address before G↓	0			0			
		Data after G †	0			0			
th	Hold time	Address after G f	0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CON	DITIONS		Sf	154LS2	59B	SN	174LS2	598	UNIT
PANAMETEN		1EST COM	Dilions,		MIN	MIN TYP MAX			TYP	MAX	UNII
VIK	V <sub>CC</sub> = MIN,	I <sub>I</sub> = - 18 mA					1.5			- 1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, I <sub>OH</sub> = - 0.4 m	V <sub>IH</sub> = 2 V, A	VIL = MAX,		2.5	3.4		2.7	3.4		V
V	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,		1 <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
VOL	VIL = MAX			IOL = 8 mA		-		<u> </u>	0.35	0.5	1 °
l <sub>1</sub>	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V					0.1			0.1	mA
Чн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V					20			20	μА
HL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V				-	- 0.4			- 0.4	mA
los§	V <sub>CC</sub> = MAX				- 20		- 100	- 20		- 100	mA
lcc	V <sub>CC</sub> = MAX,	See Note 2				27	36		22	36	mA

 $<sup>^\</sup>dagger$  For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions

# switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
tPHL	CLR	Any Q		12	18	ns
<sup>t</sup> PLH	Data	Any Q		19	30	
<sup>t</sup> PHL	Data	Anya	C: -15 ps	13	20	ns
<sup>t</sup> PLH	Address	Any Q	$C_L = 15 pF$ , $R_L = 2 k\Omega$ , See Note 3	17	27	
<sup>t</sup> PHL	Address	Anya	See Note 3	14	20	ns
tPLH	Ğ	Any Q		15	24	
<sup>t</sup> PHL	3	Any Q		15	24	ns

tpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

 $<sup>\</sup>S$  Not more than one output should be shorted at a time, and duration short-circuit should not exceed one second.

NOTE 2:  $I_{\mbox{\footnotesize{CC}}}$  is measured with the inputs grounded and the outputs open.

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74LS259BD	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	0 to 70	LS259B
SN74LS259BDR	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS259B
SN74LS259BDR.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS259B
SN74LS259BN	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS259BN
SN74LS259BN.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS259BN

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

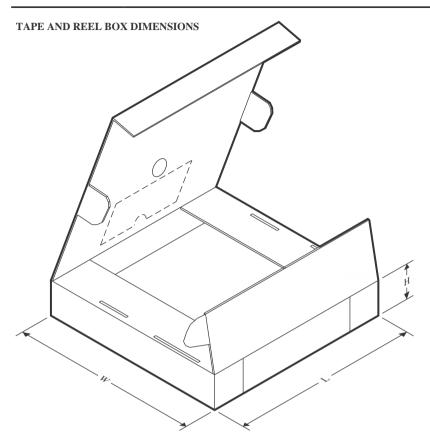
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS259BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS259BDR	SOIC	D	16	2500	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LS259BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS259BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS259BN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS259BN.A	N	PDIP	16	25	506	13.97	11230	4.32

# D (R-PDS0-G16)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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